

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Canceled).

2. (previously presented) The solder deposition method according to claim 8,

wherein said step of forming a dam includes the steps of:

forming a resin film on the surface of said substrate; and

providing an opening part in said resin film so that a dam is formed around an electrode on a substrate.

3. (previously presented) The solder deposition method according to claim 8,

wherein said dam is not removed after depositing solder.

4. (previously presented) The solder deposition method according to claim 8,

wherein said substrate is a via-on-pad structured substrate.

5-7. (Canceled).

8. (previously presented) A solder deposition method comprising the steps of:

forming a dam around an electrode on a substrate;

applying a solder precipitating composition to said substrate; and

heating the resulting substrate so as to form a solder on the surface of said electrode,

wherein said solder precipitating composition comprises a tin powder and a silver or copper complex of at least one member selected from the group consisting of aryl phosphines, alkyl phosphines and azoles.

9-12. (canceled).

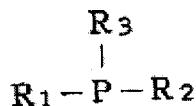
13. (previously presented) A solder deposition method comprising the steps of:
forming a dam around an electrode on a substrate;
applying a solder precipitating composition comprising a tin powder and a silver or copper complex of at least one member selected from the group consisting of aryl phosphines, alkyl phosphines and azoles to said substrate; and
heating the resulting substrate, whereby the tin powder reacts with the complex so as to precipitate a solder on the surface of said electrode.

14. (previously presented) A solder deposition method comprising the steps of:
forming a dam around an electrode on a substrate;
kneading a composition comprising tin powder and a silver or copper complex of at least one member selected from the group consisting of aryl phosphines, alkyl phosphines and azoles to form a solder precipitating composition;
applying said solder precipitating composition to said substrate; and
heating the resulting substrate so as to deposit a solder on the surface of said electrode.

15-16. (canceled).

17. (previously presented) The solder deposition method according to claim 8,

wherein the phosphine is represented by formula (1)



wherein R₁, R₂ and R₃ each represents a substituted or non-substituted aryl group, or a substituted or non-substituted chain or cyclic alkyl group having 1 to 8 carbon atoms; hydrogen of the aryl group may be substituted with an alkyl having 1 to 8 carbon atoms, an alkoxy group having 1 to 8 carbon atoms, a hydroxyl group, an amino group or a halogen atom at any position; hydrogen of the alkyl group may be substituted with an alkoxy group having 1 to 8 carbon atoms, an aryl group, a hydroxyl group, an amino group or a halogen at any position; and R₁, R₂ and R₃ may be the same or different.

18. (previously presented) The solder deposition method according to claim 8,

wherein the aryl phosphines is triphenyl phosphine, tri(o-, m- or p-tolyl) phosphine or tri(p-methoxyphenyl) phosphine.

19. (previously presented) The solder deposition method according to claim 8,

wherein the alkyl phosphines is tributyl phosphine, trioctyl phosphine, tris(3-hydroxypropyl) phosphine, or tribenzyl phosphine.

20. (previously presented) The solder deposition method according to claim 8,

wherein the complex of aryl phosphines or alkyl phosphines is cationic and the counter anion is

an organic sulfonic ion, organic carboxylic ion, halogen ion, nitric ion or sulfuric ion, or mixtures thereof.

21. (previously presented) The solder deposition method according to claim 20, wherein the organic sulfonic acid is a methanesulfonic acid, 2-hydroxyethanesulfonic acid, 2-hydroxypropane-1-sulfonic acid, trichloromethanesulfonic acid, trifluoromethanesulfonic acid, benzenesulfonic acid, toluenesulfonic acid, phenolsulfonic acid, cresolsulfonic acid, anisolesulfonic acid or naphthalenesulfonic acid.

22. (previously presented) The solder deposition method according to claim 20, wherein the organic carboxylic acid is a monocarboxylic acid, dicarboxylic acid, hydroxycarboxylic acid, or halogen-substituted carboxylic acid.

23. (previously presented) The solder deposition method according to claim 22, wherein the organic carboxylic acid is formic acid, acetic acid, propionic acid, butanoic acid, octanoic acid, oxalic acid, malonic acid, succinic acid, lactic acid, glycolic acid, tartaric acid, citric acid, monochloroacetic acid, dichloroacetic acid, trichloroacetic acid, trifluoroacetic acid or perfluoropropionic acid.

24. (previously presented) The solder deposition method according to claim 8, wherein the azoles is tetrazole, triazole, benzotriazole, imidazole, benzimidazole, pyrazole, indazole, thiazole, benzothiazole, oxazole, benzoxazole, pyrrole, indole and derivatives thereof, or a mixture of two or more.

25. (previously presented) The solder deposition method according to claim 24, wherein the azole is tetrazole, 5-mercaptop-1-phenyltetrazole, 1,2,3-triazole, 1,2,4-triazole, 3-mercaptop-1,2,4-triazole, benzotriazole, tolyltriazole, carboxybenzotriazole, imidazole, 2-mercaptopimidazole, benzimidazole, 2-octylbenzimidazole, 2-phenylbenzimidazole, 2-mercaptobenzimidazole, 2-methylthiobenzimidazole, pyrazole, indazole, thiazole, benzothiazole, 2-phenylbenzothiazole, 2-mercaptobenzothiazole, 2-methylthiobenzothiazole, isoxazole, anthranil, benzoxazole, 2-phenylbenzoxazole, 2-mercaptobenzoxazole, pyrrole, 4,5,6,7-tetrahydroindole or indole.

26-29. (canceled).